CLAIMS

1. A method comprising:

attaching a die to a printed circuit board;

fabricating a hole in said printed circuit board adjacent to said die;

filling said hole with a mold compound, said mold compound surrounding and covering said die, said mold compound being thereby locked into said printed circuit board.

2. The method of claim 1 wherein said hole is a through hole.

3. The method of claim 1 wherein said hole is a blind hole.

4. The method of claim 1 further comprising a step of bonding a first end of a bond wire to a die bonding pad on said die and a second end of said bond wire to a printed circuit board bonding location on said printed circuit board, said step of bonding being performed after said step of attaching but prior to said step of fabricating.

5. The method of claim 1 wherein said mold compound is selected from the group consisting of multifunctional epoxy, novolac, and biphenyl resin.

6. The method of claim 1 wherein said attaching step comprises applying a die attach to attach said die onto said printed circuit board.

7. The method of claim 6 wherein said die attach is selected from the group consisting of electrical conductive, electrically insulative, thermoset adhesive, and thermoplastic adhesive.

8. The method of claim 1 wherein said printed circuit board comprises a first layer of metal below said die.

9. The method of claim 8 wherein said attaching step comprises applying a die attach to attach said die onto said first layer of metal.

10. The method of claim 8 wherein said first layer of metal comprises gold-plated copper.

11. A structure comprising:

a printed circuit board including a die attached to said printed circuit board;

a hole in said printed circuit board, said hole being adjacent to said die, said hole being filled with a mold compound, said mold compound surrounding and covering said die, wherein said mold compound is locked into said printed circuit board.

12. The structure of claim 11 wherein said hole is a through hole.

13. The structure of claim 11 wherein said hole is a blind hole.

14. The structure of claim 11 further comprising a bond wire, wherein a first end of said bond wire is bonded to a die bonding pad on said die and a second end of said bond wire is bonded to a printed circuit board bonding location on said printed circuit board.

15. The structure of claim 11 wherein said mold compound is selected from the group consisting of multifunctional epoxy, novolac, and biphenyl resin

16. The structure of claim 11 further comprising a layer of die attach between said die and said printed circuit board.

17. The structure of claim 11 wherein said printed circuit board comprises a first layer of metal below said die.

18. The structure of claim 17 further comprising a layer of die attach between said die and said first layer of metal.

19. The structure of claim 17 wherein said first layer of metal comprises gold-plated copper.